

Amendments to the Claims:

This listing of claims will replace all prior versions and listing of claims in the application:

Claims 1-17 (cancelled)

18. (Previously presented) A process for improving the solderability of a metal surface, said process comprising treating the metal surface with an immersion silver plating solution, said solution comprising:

- a). a soluble source of silver ions;
- b). an acid;
- c). an additive selected from the group consisting of fatty amines, fatty amides, quaternary salts, and ethoxylated versions of any of the foregoing.

19. (Previously presented) A process according to claim 18 wherein the silver plating solution also comprises material selected from the group consisting of imidazoles, benzimidazoles, imidazole derivatives and benzimidazole derivatives.

20. (Previously presented) A process according to claim 18 wherein the silver plating solution also comprises an oxidant.

21. (Previously presented) A process according to claim 18 wherein the metal surface comprises copper.

22. (Previously presented) A process according to claim 21 wherein the silver plating solution also comprises a material selected from the group consisting of imidazoles, benzimidazoles, imidazole derivatives, and benzimidazole derivatives.

23. (Previously presented) A process according to claim 22 wherein the silver plating solution also comprises an oxidant.

24. (Currently amended) An immersion silver plating solution comprising

- (i) a soluble source of silver ions,
- (ii) an acid and
- (iii) an additive selected from the group consisting of ~~an additive selected from the group consisting of~~ fatty amines, fatty amides, quaternary salts, and ethoxylated versions of any of the foregoing.

25. (Previously presented) An immersion plating solution according to claim 24 also comprising a material selected from the group consisting of imidazoles, benzimidazoles, imidazole derivatives, and benzimidazole derivatives.

26. (Previously presented) An immersion plating solution according to claim 24 also comprising an oxidant.

Claims 27-31 (Cancelled).

32. (Previously presented) A process for improving the solderability of a metal surface, said process comprising:

a). contacting the metal surface with an immersion silver plating solution thereby producing an immersion silver plate upon the metal surface; and thereafter

b). treating the immersion silver plated metal surface with a solution comprising an additive selected from the group consisting of fatty amines, fatty amides, quaternary salts, and ethoxylated versions of any of the foregoing.

33. (Previously presented) A process according to claim 32 wherein the silver plating solution comprises a material selected from the group consisting of imidazoles, benzimidazoles, imidazole derivatives and benzimidazole derivatives.

34. (Previously presented) A process according to claim 32 wherein the silver plating solution also comprises an oxidant.

35. (Previously presented) A process according to claim 32 wherein the metal surface comprises copper.

36. (Previously presented) A process according to claim 35 wherein the silver plating solution comprises a material selected from the group consisting of imidazoles, benzimidazoles, imidazole derivatives and benzimidazole derivatives.

37. (Previously presented) A process according to claim 36 wherein the silver plating solution also comprises an oxidant.

38. (Previously presented) An immersion silver plating solution comprising an additive selected from the group

consisting of fatty amines, fatty amides, quaternary salts, and ethoxylated versions of any of the foregoing.

39. (Previously presented) An immersion plating solution according to claim 38 also comprising a material selected from the group consisting of imidazoles, benzimidazoles, imidazole derivatives, and benzimidazole derivatives.

40. (Previously presented) An immersion plating solution according to claim 38 also comprising an oxidant.